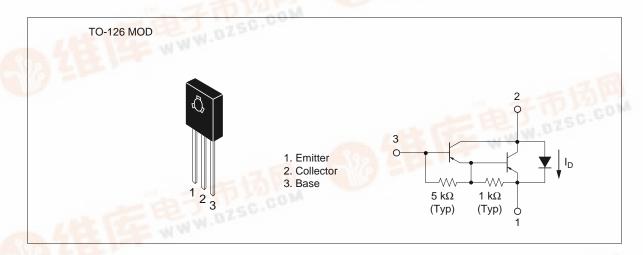
Silicon PNP Epitaxial

# HITACHI

#### Application

Low frequency power amplifier complementary pair with 2SD1376(K)

#### Outline





## **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

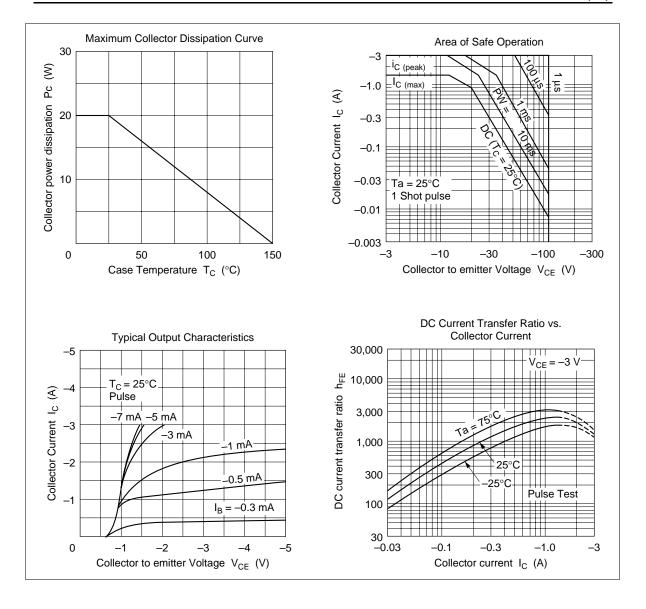
Item	Symbol	Rating	Unit
Collector to base voltage	$V_{\text{CBO}}$	-120	V
Collector to emitter voltage	$V_{\text{CEO}}$	-120	V
Emitter to base voltage	$V_{EBO}$	<b>-7</b>	V
Collector current	I <sub>c</sub>	-1.5	A
Collector peak current	C(peak)	-3.0	A
Collector power dissipation	P <sub>c</sub> *1	20	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
C to E diode forward current	<sub>D</sub> *1	1.5	A

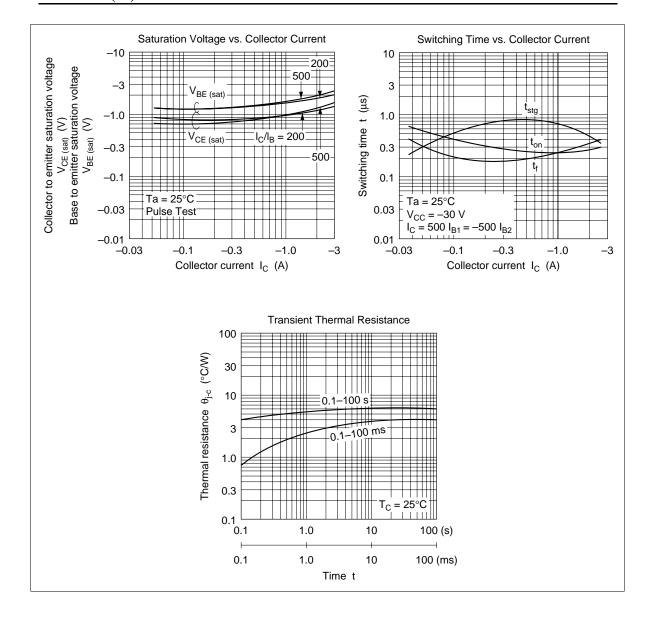
Note: 1. Value at  $T_c = 25^{\circ}C$ 

### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

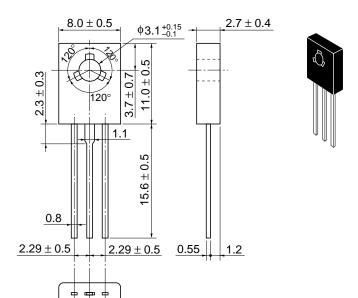
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-120	_	_	V	$I_{c} = -10 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	<b>-7</b>	_	_	V	$I_{\rm E} = -50 \text{ mA}, I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	-100	μΑ	$V_{CB} = -120 \text{ V}, I_{E} = 0$
	I <sub>CEO</sub>	_	_	-10	μΑ	$V_{CE} = -100 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h <sub>FE</sub>	2000	_	30000		$V_{CE} = -3 \text{ V}, I_{C} = -1 \text{ A}^{*1}$
Collector to emitter saturation	V <sub>CE(sat)1</sub>	_	_	-1.5	V	$I_{\rm C} = -1 \text{ A}, I_{\rm B} = -1 \text{ mA}^{*1}$
voltage	V <sub>CE(sat)2</sub>	_	_	-2.0	V	$I_{\rm C} = -1.5 \text{ A}, I_{\rm B} = -1.5 \text{ mA}^{*1}$
Base to emitter saturation	$V_{BE(sat)1}$	_	_	-2.0	V	$I_{\rm C} = -1 \text{ A}, I_{\rm B} = -1 \text{ mA}^{*1}$
voltage	$V_{BE(sat)2}$	_	_	-2.5	V	$I_{\rm C} = -1.5 \text{ A}, I_{\rm B} = -1.5 \text{ mA}^{*1}$
C to E diode forward voltage	$V_{D}$	_	_	3.0	V	$I_D = 1.5 A^{*1}$
Turn on time	t <sub>on</sub>	_	0.5	_	μs	$I_{\rm C} = -1 \text{ A}, I_{\rm B1} = -I_{\rm B2} = -1 \text{ mA}$
Turn off time	t <sub>off</sub>	_	2.0	_	μs	_

Note: 1. Pulse test









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